保密等级：机密

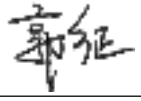
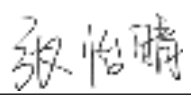
SPECIFICATION

产品规格书

SKI.WB821CU.2

IEEE 802.11a/b/g/n/ac 1T1R USB Wi-Fi Module

Integrated Bluetooth 2.1+BR/EDR/4.2

Approved by Shikun		
Checked by 审核	Rechecked by 复审	Approved by 批准
		

Please send the original back to us after you have approved and signed.
客户承认签章后敬请寄回正本一份。

Approved by customer		
Comments 确认意见	Approved by 批准签字	Company's seal 盖章
Customer's Name:		

REVISION HISTORY

VERSION	DATE	BOARD ID	PAGE	DESCRIPTION	AUTHOR
V0	2020.04.21	SKI.WB821CU.2 B20165	All	First Issued.	Yve

Content

1. Introduction（简介）

SKI.WB821CU.2 module is based on Realtek RTL8821CU-CG solution.

RTL8821CU-CG is a highly integrated single chip which features a low power 1x1 11a/b/g/n/ac dual-band Wi-Fi subsystem and a Bluetooth subsystem. The Wi-Fi subsystem contains the 802.11a/b/g/n/ac radio, baseband, and MAC that are designed to meet both the low power and high throughput application. The Bluetooth subsystem contains the Bluetooth radio which complies with Bluetooth v2.1+BR/EDR and v4.2, baseband, link controller. This documentation describes the engineering requirements specification.

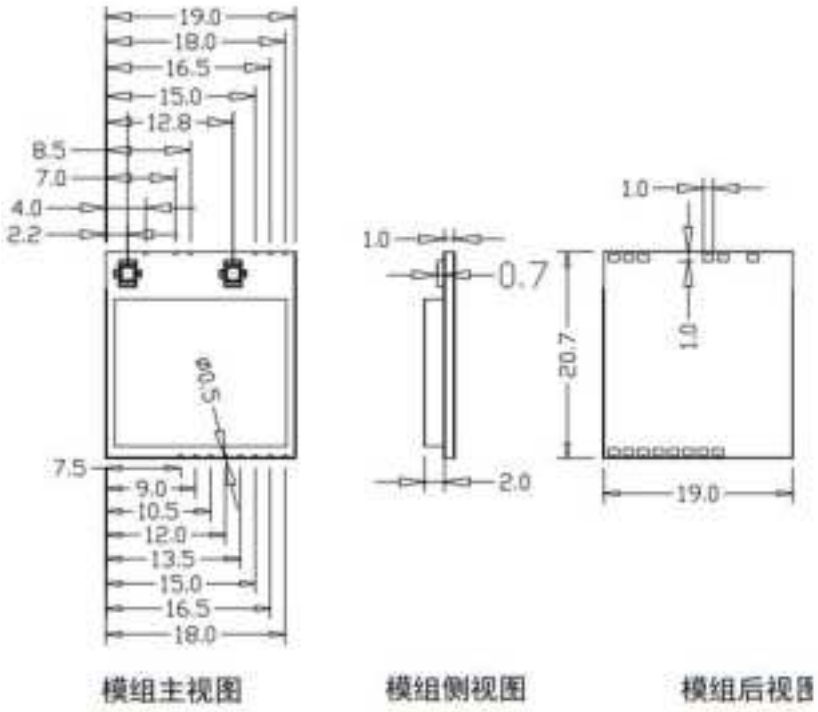
SKI.WB821CU.2 模组是基于 Realtek 的 RTL8821CU-CG 方案开发，RTL8821CU-CG 是一款高集成单芯片和低功耗的单发单收的双频 WIFI 芯片，支持 802.11a/b/g/n/ac，同时此 IC 支持蓝牙 v2.1+BR/EDR 和 v4.2，主要用于 TV 驱动领域。本文档描述了产品的设计要求规范。

2. FEATURES（特性）

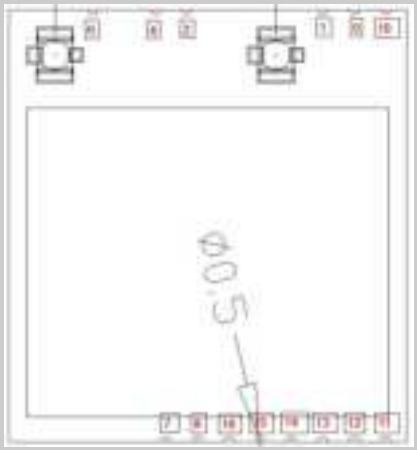
Reserving System **接收制式**	IEEE Std. 802.11a
	IEEE Std. 802.11b
	IEEE Std. 802.11g
	IEEE Std. 802.11n
	IEEE Std. 802.11ac
	Bluetooth 2.1+BR/EDR/4.2
Chip Solution **芯片方案**	RTL8821CU-CG
Band **波段**	2.4/5GHz
Dimensions **尺寸**	19mm×20.7mm×3.0mm

型号	安装方式	支持标准	频段	天线接口	备注
SKI.WB821CU.2	SMD	IEEE 802.11a/b/g/n/ac+ Bluetooth 2.1+BR/EDR/4.2	2.4/5GHz	三代 IPEX	19mm×20.7mm ×3.0mm

4. Package Outline and Mounting（外形及安装尺寸）



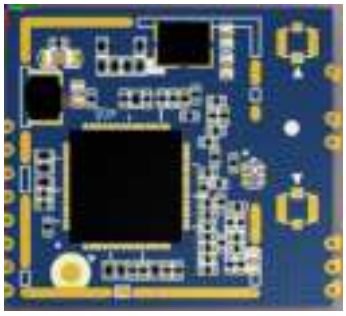
5. Pin Definition（引脚定义）



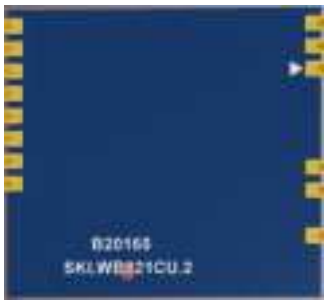
PIN	SYMBOL	DESCRIPTION
1	LED	LED0\ LED 灯控制
2	AGND	Ground\ 接地
4	AGND	Ground\接地
6	AGND	Ground\接地
7	BT_DIS	BT Disable，L Active\ 蓝牙使能控制，高电平使能，默认高电平
8	WL_DIS	WIFI Disable，L Active\ WIFI 使能控制，高电平使能，默认高电平
9	VDD33	3.3V input\ 3.3V 供电输入
10	AGND	Ground\接地
11	WL_USB_DM	WLAN USB2.0 DM Signal\ USB 差分负电压信号
12	WL_USB_DP	WLAN USB2.0 DP Signal\ USB 差分正电压信号
13	AGND	Ground\接地
14	PDN	Power Down，L Active\ 供电使能，高电平有效，默认高电平
15	D_WAKE_H	WIFI Device Wake Host， L Active\ WIFI 从机唤醒主机，低电平有效
16	H_WAKE_D	Host Wake WIFI DeviceL， Active\ 主机唤醒 WIFI 从机，低电平有效

注：此模块没有 PIN3、PIN5

6. Product Pictures（实物图片）



正视图（**top view**）



背视图（**bottom view**）

产品铭牌内容如下（高温贴纸）：

7. Key Materials（关键物料）

序号	关键件名称	型号	规格/材料	备注
1	集成电路	RTL8821CU-CG	QFN56	
2	PCB	SKI.WB821CU.2	FR-4,4LAY	
3	晶体振荡器	PF4040M00012T2115138	40MHz	
4	双工器	SLFD18-2R450G-06T		

8. General Requirements（一般要求）

No.	Feature	Description
8-1	Operation Voltage\ 工作电压范围	3.3V+/-0.3
8-2	Current Consumption\ 最大电流	300mA
8-3	Ripple\ 波纹	≤70mV
8-4	Operation Temperature\ 工作温度范围	0°C to +40°C
8-5	Antenna Type\ 天线类型	External antenna\ 外置天线
8-6	USB	High Speed USB 2.0 Interface\ 高速 USB2.0 接口
8-7	Storage Temperature\ 存储温度	-20°C to +85°C

9. Electrical Characteristics（电气特性）

The Test for electrical specification was performed under the following condition unless otherwise specified.Ambient condition Temperature :25℃ ± 5℃ ;Power supply voltages： 3.3V (±10%) input power at the Module.

除非另有说明， 电气规范试验是在下列条件下进行的。 环境条件温度： 25℃±5℃； 电源电压： 模块输上入电压 3.3V（±10%） .

9.1 IEEE 802.11b Section

Items	Contents				
Specification	IEEE802.11b				
Mode	CCK				
Channel	CH1 to CH13				
Data rate	1, 2, 5.5, 11Mbps				
TX Characteristics	Min.	Typ.	Max.	Unit	Remark
1. Power Levels(Calibrated)					
1) For Each antenna port	14	16	18	dBm	
2. Spectrum Mask @ target power					
1) fc +/-11MHz to +/-22MHz	-	-	-30	dBr	
2) fc > +/-22MHz	-	-	-50	dBr	
3 Constellation Error(EVM)@ target power					
1) 1Mbps	-	-	-10	dB	
2) 2Mbps	-	-	-10	dB	
3) 5.5Mbps	-	-	-10	dB	
4) 11Mbps	-	-	-10	dB	
4. Frequency Error	-25	-	25	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5 Minimum Input Level Sensitivity (each chain)					
1) 1Mbps (FER ≤8%)	-	-	-83	dBm	

2) 2Mbps (FER ≦8%)	-	-	-80	dBm	
3) 5.5Mbps (FER ≦8%)	-	-	-79	dBm	
4) 11Mbps (FER ≦8%)	-	-	-76	dBm	
6 Maximum Input Level (FER ≦8%)	-10	-	-	dBm	

9.2 IEEE 802.11g Section

Items	Contents				
Specification	IEEE802.11g				
Mode	OFDM				
Channel	CH1 to CH13				
Data rate	6, 9, 12, 18, 24, 36, 48, 54Mbps				
TX Characteristics	Min.	Typ.	Max.	Unit	Remark
1. Power Levels					
1) For Each antenna port	12	14	16	dBm	
2. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-40	dBr	
3 Constellation Error(EVM)@ target power					
1) 6Mbps	-	-	-5	dB	
2) 9Mbps	-	-	-8	dB	
3) 12Mbps	-	-	-10	dB	
4) 18Mbps	-	-	-13	dB	
5) 24Mbps	-	-	-16	dB	
6) 36Mbps	-	-	-19	dB	
7) 48Mbps	-	-	-22	dB	
8) 54Mbps	-	-	-25	dB	
4 Frequency Error	-25	-	25	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5 Minimum Input Level Sensitivity (each chain)					
1) 6Mbps (PER ≦10%)	-	-	-85	dBm	
2) 9Mbps (PER ≦10%)	-	-	-84	dBm	
3) 12Mbps (PER ≦10%)	-	-	-82	dBm	
4) 18Mbps (PER ≦10%)	-	-	-80	dBm	
5) 24Mbps (PER ≦10%)	-	-	-77	dBm	
6) 36Mbps (PER ≦10%)	-	-	-73	dBm	
7) 48Mbps (PER ≦10%)	-	-	-69	dBm	
8) 54Mbps (PER ≦10%)	-	-	-65	dBm	
6 Maximum Input Level (PER ≦10%)	-20	-	-	dBm	

9.3 IEEE 802.11n HT20 Section(2.4GHz)

Items	Contents				
Specification	EEE802.11n HT20 @ 2.4GHz				
Mode	OFDM				
Channel	CH1 to CH13				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
2. Power Levels					
1) For Each antenna port	11	13	15	dBm	
3. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-45	dBr	
4. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
5. Frequency Error	-25	-	25	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
6. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≦10%)	-	-	-82	dBm	
2) MCS1 (PER ≦10%)	-	-	-79	dBm	
3) MCS2 (PER ≦10%)	-	-	-77	dBm	
4) MCS3 (PER ≦10%)	-	-	-74	dBm	
5) MCS4 (PER ≦10%)	-	-	-70	dBm	
6) MCS5 (PER ≦10%)	-	-	-66	dBm	
7) MCS6 (PER ≦10%)	-	-	-65	dBm	
8) MCS7 (PER ≦10%)	-	-	-64	dBm	
7. Maximum Input Level (PER ≦10%)	-20	-	-	dBm	

9.4 IEEE 802.11n HT40 Section(2.4GHz)

Items	Contents				
Specification	IEEE802.11n HT40 @ 2.4GHz				
Mode	OFDM				
Channel	CH3 to CH11				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
	Min.	Typ.	Max.	Unit	Remark
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For Each antenna port	11	13	15	dBm	
2. Spectrum Mask @target power					
1) at fc +/-22MHz	-	-	-20	dBr	
2) at fc +/-40MHz	-	-	-28	dBr	
3) at fc > +/-60MHz	-	-	-45	dBr	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
4. Frequency Error	-25	-	25	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≦10%)	-	-	-79	dBm	
2) MCS1 (PER ≦10%)	-	-	-76	dBm	
3) MCS2 (PER ≦10%)	-	-	-74	dBm	
4) MCS3 (PER ≦10%)	-	-	-71	dBm	
5) MCS4 (PER ≦10%)	-	-	-67	dBm	
6) MCS5 (PER ≦10%)	-	-	-63	dBm	
7) MCS6 (PER ≦10%)	-	-	-62	dBm	
8) MCS7 (PER ≦10%)	-	-	-61	dBm	
6. Maximum Input Level (PER ≦10%)	-20	-	-	dBm	

9.5 IEEE 802.11a Section

Items	Contents				
Specification	IEEE802.11a				
Mode	OFDM				
Channel	CH36 to CH165				
Data rate	6, 9, 12, 18, 24, 36, 48, 54Mbps				
TX Characteristics	Min.	Typ.	Max.	Unit	Remark
1. Power Levels					
1) For Each antenna port	9	11	13	dBm	
2. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-40	dBr	
3 Constellation Error(EVM)@ target power					
1) 6Mbps	-	-	-5	dB	
2) 9Mbps	-	-	-8	dB	
3) 12Mbps	-	-	-10	dB	
4) 18Mbps	-	-	-13	dB	
5) 24Mbps	-	-	-16	dB	
6) 36Mbps	-	-	-19	dB	
7) 48Mbps	-	-	-22	dB	
8) 54Mbps	-	-	-25	dB	
4 Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
5 Minimum Input Level Sensitivity (each chain)					
1) 6Mbps (PER ≦10%)	-	-	-82	dBm	
2) 9Mbps (PER ≦10%)	-	-	-81	dBm	
3) 12Mbps (PER ≦10%)	-	-	-79	dBm	
4) 18Mbps (PER ≦10%)	-	-	-77	dBm	
5) 24Mbps (PER ≦10%)	-	-	-74	dBm	
6) 36Mbps (PER ≦10%)	-	-	-70	dBm	
7) 48Mbps (PER ≦10%)	-	-	-66	dBm	
8) 54Mbps (PER ≦10%)	-	-	-65	dBm	
6 Maximum Input Level (PER ≦10%)	-30	-	-	dBm	

9.6 IEEE 802.11n HT20 Section(5GHz)

Items	Contents				
Specification	EEE802.11n HT20 @ 5GHz				
Mode	BPSK, QPSK, 16QAM, 64QAM and OFDM				
Channel	CH36 to CH165				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
TX Characteristics	Min.	Typ.	Max.	Unit	
2. Power Levels					
1) For Each antenna port	8	10	12	dBm	
3. Spectrum Mask @ target power					
1) at fc +/-11MHz	-	-	-20	dBr	
2) at fc +/-20MHz	-	-	-28	dBr	
3) at fc > +/-30MHz	-	-	-45	dBr	
4. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
5. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
7. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≦10%)	-	-	-82	dBm	
2) MCS1 (PER ≦10%)	-	-	-79	dBm	
3) MCS2 (PER ≦10%)	-	-	-77	dBm	
4) MCS3 (PER ≦10%)	-	-	-74	dBm	
5) MCS4 (PER ≦10%)	-	-	-70	dBm	
6) MCS5 (PER ≦10%)	-	-	-66	dBm	
7) MCS6 (PER ≦10%)	-	-	-65	dBm	
8) MCS7 (PER ≦10%)	-	-	-64	dBm	
7. Maximum Input Level (PER ≦10%)	-30	-	-	dBm	

9.7 IEEE 802.11n HT40 Section(5GHz)

Items	Contents				
Specification	IEEE802.11n HT40 @ 5GHz				
Mode	BPSK, QPSK, 16QAM, 64QAM and OFDM				
Channel	CH38 to CH163				
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7				
	Min.	Typ.	Max.	Unit	Remark
TX Characteristics	Min.	Typ.	Max.	Unit	
1. Power Levels (Calibrated)					
1) For Each antenna port	8	10	12	dBm	
2. Spectrum Mask @target power					
1) at fc +/-21MHz	-	-	-20	dBr	
2) at fc +/-40MHz	-	-	-28	dBr	
3) at fc > +/-60MHz	-	-	-45	dBr	
3. Constellation Error(EVM)@ target power					
1) MCS0	-	-	-5	dB	
2) MCS1	-	-	-10	dB	
3) MCS2	-	-	-13	dB	
4) MCS3	-	-	-16	dB	
5) MCS4	-	-	-19	dB	
6) MCS5	-	-	-22	dB	
7) MCS6	-	-	-25	dB	
8) MCS7	-	-	-28	dB	
4. Frequency Error	-20	-	20	ppm	
RX Characteristics	Min.	Typ.	Max.	Unit	
6. Minimum Input Level Sensitivity (each chain)					
1) MCS0 (PER ≦10%)	-	-	-79	dBm	
2) MCS1 (PER ≦10%)	-	-	-76	dBm	
3) MCS2 (PER ≦10%)	-	-	-74	dBm	
4) MCS3 (PER ≦10%)	-	-	-71	dBm	
5) MCS4 (PER ≦10%)	-	-	-67	dBm	
6) MCS5 (PER ≦10%)	-	-	-63	dBm	
7) MCS6 (PER ≦10%)	-	-	-62	dBm	
8) MCS7 (PER ≦10%)	-	-	-61	dBm	
6. Maximum Input Level (PER ≦10%)	-30	-	-	dBm	

9.8 IEEE 802.11ac Section

Items	Contents						
Specification	IEEE802.11ac						
Mode	BPSK, QPSK, 16QAM, 64QAM ,256QAM and OFDM						
Channel	CH36 to CH165 VHT20 CH38 to CH163 VHT40 CH42 to CH157 VHT80						
Data rate (MCS index)	MCS0/1/2/3/4/5/6/7/8/9						
	Min.	Typ.	Max.			Unit	Remark
TX Characteristics	Min.	Typ.	Max.			Unit	
1. Power Levels (Calibrated)							
1) For Each antenna port	8	10	12			dBm	
2. Spectrum Mask @VHT20/VHT40/VHT80 target power							
1) at fc +/-11MHz/21MHz/41MHz	-	-	-20			dBr	
2) at fc +/-20MHz/40MHz/80MHz	-	-	-28			dBr	
3) at fc +/-30MHz/60MHz/120MHz	-	-	-40			dBr	
3. Constellation Error(EVM)@ target power							
1) MCS0	-	-	-5			dB	
2) MCS1	-	-	-10			dB	
3) MCS2	-	-	-13			dB	
4) MCS3	-	-	-16			dB	
5) MCS4	-	-	-19			dB	
6) MCS5	-	-	-22			dB	
7) MCS6	-	-	-25			dB	
8) MCS7	-	-	-27			dB	
9) MCS8			-30			dB	
10) MCS9			-32			dB	
4. Frequency Error	-20	-	20			ppm	
RX Characteristics	Min.	Typ.	Max.			Unit	
7. Minimum Input Level Sensitivity (each chain)			VHT 20	VHT 40	VHT 80		
1) MCS0 (PER ≦10%)	-	-	-82	-79	-76	dBm	
2) MCS1 (PER ≦10%)	-	-	-79	-76	-73	dBm	
3) MCS2 (PER ≦10%)	-	-	-77	-74	-71	dBm	
4) MCS3 (PER ≦10%)	-	-	-74	-71	-68	dBm	
5) MCS4 (PER ≦10%)	-	-	-70	-67	-64	dBm	
6) MCS5 (PER ≦10%)	-	-	-66	-63	-60	dBm	
7) MCS6 (PER ≦10%)	-	-	-65	-62	-59	dBm	
8) MCS7 (PER ≦10%)	-	-	-64	-61	-58	dBm	
9) MCS8 (PER ≦10%)			-59	-56	-53	dBm	

10) MCS9 (PER ≦10%)			-57	-54	-51	dBm	
6. Maximum Input Level (PER ≦10%)	-30	-	-			dBm	

9.9 Bluetooth Section

Items	Contents				
Specification	BT2.1+BR/EDR/4.2				
Mode	FHSS,GFSK,DPSK,DQPSK				
Number of Channel	79 Channels				
Frequency Band	2.402 GHz ~2.480GHz				
	Min.	Typ.	Max.	Unit	Remark
1. Output Power		4	-	dBm	
2. Gain step	2	4	8	dB	
3. Receiver sensitivity (BER ≦0.1%)	-	-93.5	-80	dBm	
4. Maximum usable signal (BER ≦0.1%)	-	-5	-		
5. C/I co-channel (BER<0.1%)	-	4	11	dB	
6. C/I 1MHz (BER<0.1%)	-	-14	0	dB	
7. C/I 2MHz (BER<0.1%)	-	-42	-30	dB	
8. C/I≥3MHz (BER<0.1%)	-	-49	-40	dB	
9. C/I Image channel (BER<0.1%)	-	-25	-9	dB	
10. C/I Image 1MHz (BER<0.1%)	-	-50	-20	dB	
11. Inter-modulation	-	-13	-	dB	
12. Out-of-band blocking					
1). 30MHz to 2000MHz	-10	-	-	dBm	
2). 2000MHz to 2399MHz	-27	-	-	dBm	
3). 2498MHz to 3000MHz	-27	-	-	dBm	
4). 3000MHz to 12.75GHz	-10	-	-	dBm	
13. Modulation characteristics					
1). Δf1avg	140	157	175	KHz	
2). Δf2max (For at least 99.9% of all Δf2max)	115	140	-	KHz	
3). Δf1avg /Δf2avg	0.8	0.98	-	KHz	
14. ICFT	-75	±20	+75	KHz	
15. Carrier frequency drift					
1). One slot packet (DH1)	-25	±15	+25	KHz	
2). Two slot packet (DH3)	-40	±15	+40	KHz	
3). Five slot packet (DH5)	-40	±15	+40	KHz	
4). Max drift rate	-	6	20	KHz/50us	
16. TX output spectrum(20dB bandwidth)	-	922	1000	KHz	
17. In-Band spurious emission					
1). ±2MHz offset	-	-45	-20	dBm	
2). ±3MHz offset	-	-48	-40	dBm	
3). >±3MHz offset	-	-48	-40	dBm	

10. Mechanical,Environmental and Reliability Tests

（机械、环境和可靠性测试）

Test Items		Test Conditions	Qty	Criteria Condition
10-1	**Drop test**	The packed samples within 100Kg can be tested Drop height: Face Side: 800/600/450mm Edge line: 600/450/350mm Drop time: 1 each Face and edge.	1xBox	After drop test, the outer box and inner box will not been broken by appearance visual inspection.
10-2	**Vibration test**	X-Y-Z direction, first Frequency changing from 10Hz to 30Hz to 10Hz,amplitude 0.75mm, 5 times vibrations, then frequency Changing from 30Hz to 55 Hz to 30 Hz, amplitude 0.15mm, 5 time vibration.	3	After test, the Appearance, Power EVM and Frequency error shall be satisfied with the specification.
10-3	**Impact test**	Impact acceleration: 50m/sec2; Impact duration: 16ms; Impact times: 1000.	3	After test, the Appearance, Power EVM and Frequency error shall be satisfied with the specification.
10-4	**Soldering ability test**	Soldering temperature: 235±5℃ Soldering duration: 2±0.5S	3	1.After soldering, the soldered area must be covered by a smooth bright solder layer, some deficiencies such as a small amount of the pinhole, not wetting are allowed, but the deficiencies can not be in the same place; 2.At least 90% of soldered area shall be covered continuously by the soldering material.
10-5	**Humidity test**	Leave samples in 40±3℃, 93% RH @ 96 hours	3	Leave samples in standard test condition for 2 hours then test, the Appearance, Power, EVM and Frequency error functional parameter shall be satisfied with the test specification.

10-6	**High temperature load life test**	Thermostat cabinet temperature: 55±5℃ Applied voltage: 110% rated voltage Working duration: 200 hour (Supply Voltage Cycle 23h power on, 1h power off)	60	After test, leave samples in standard condition for 1 hour and test, Power, EVM and Frequency error shall be satisfied with the test specification.
10-7	**High temperature load test**	Temperature: 55±5℃ Samples work for 16 hours	3	After test, the Appearance, Power, EVM and Frequency error shall be Satisfied with the test specification.
10-8	**Low temperature storage test**	Leave the samples in -25±3℃@24 hours	3	Leave samples in standard test condition for 2 hours then test, the Appearance, Power, EVM and Frequency error shall be satisfied with the test specification.
10-9	**Low temperature load test**	Leave samples in -15±3℃@ 2 hours, samples' function shall be normal, the let samples work for 1 hour	3	After test, leave the samples in standard condition and tested the Appearance, Power, EVM and Frequency error shall be satisfied with the test specification.
10-10	**Temperature circle test**	One cycle duration -10±3℃@3H 40±3℃ @3H Total cycle: 10x	3	After test, leave the samples in standard condition and tested Power EVM and Frequency error shall be qualified and all the characters shall be satisfied with the test specification.
10-11	**Continuous TP test**	Twice cycle duration -10±3℃@4H +60±3℃@4H, +25@2H@2H	3	During test, There will not been appeared signal disconnection or interruption between DUT and AP.
10-12	**ESD**	Discharge voltage: 1kV C: 150pF Discharge resistance：330Ω Positive10 times 1 time for each second	3	The products can recoverable smoothly after ESD test.

11. Package（包装）

（1）编带尺寸：
暂无

（2）编带方向：（箭头代表编带走向）
暂无
（3）包装示意图：
暂无
（4）标签样式：

内盒标签示例【具体内容根据系统打印为准】

12. Software Requirements（软件要求）

The driver supports the following operating systems: Microsoft Windows XP, Vista and Win7.
驱动程序支持以下操作系统：微软 Windows XP，Vista 和 win7。